

# Signal height in Silicon Pixel Detectors irradiated with Pions and Protons

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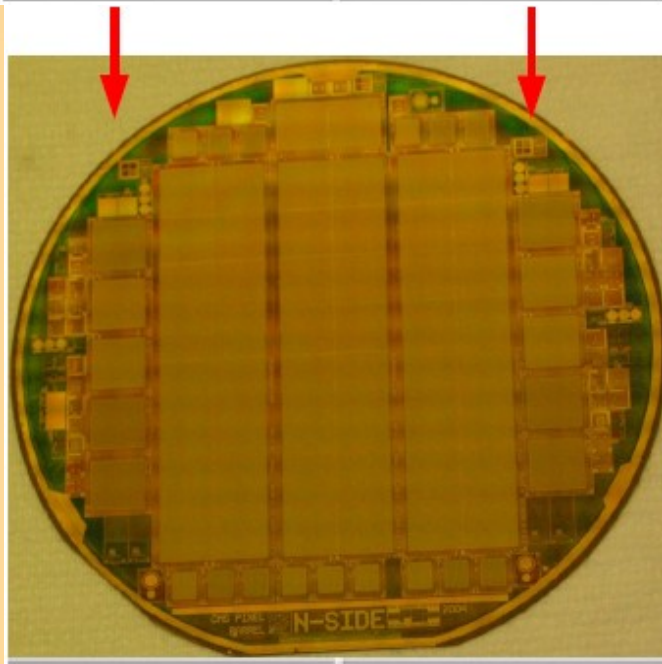
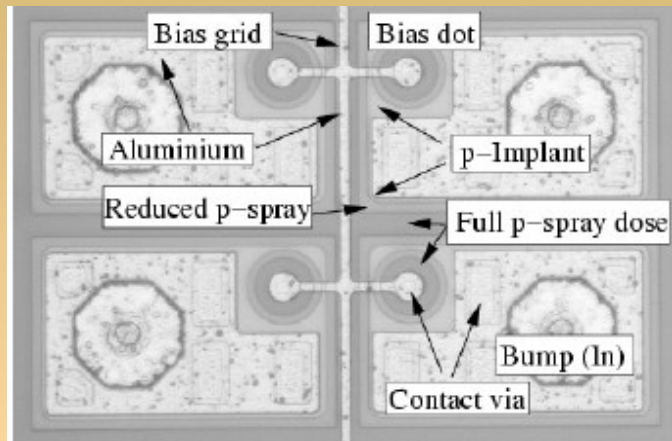
Geneva

November 11 2008

# Goals

- Study the change of the sensor behavior due to irradiation.
  - The following parameters were measured:
    - Signal height
    - Depletion voltage
    - Noise
    - Leak current

# The Samples



- Single chip sensors from CMS Barrel Pixel Detector
  - production wafers
    - N-on-n
    - DOFZ ( $\rho \sim 3.7 \text{ K } \Omega \text{ cm}$ )
    - P-spray isolation
  - 4 non-irradiated sensors (for contrast)
  - 7 groups of irradiated sensors exposed to fluences up to  $5.1 \times 10^{15} \text{ Neq/cm}^2$

# Irradiation

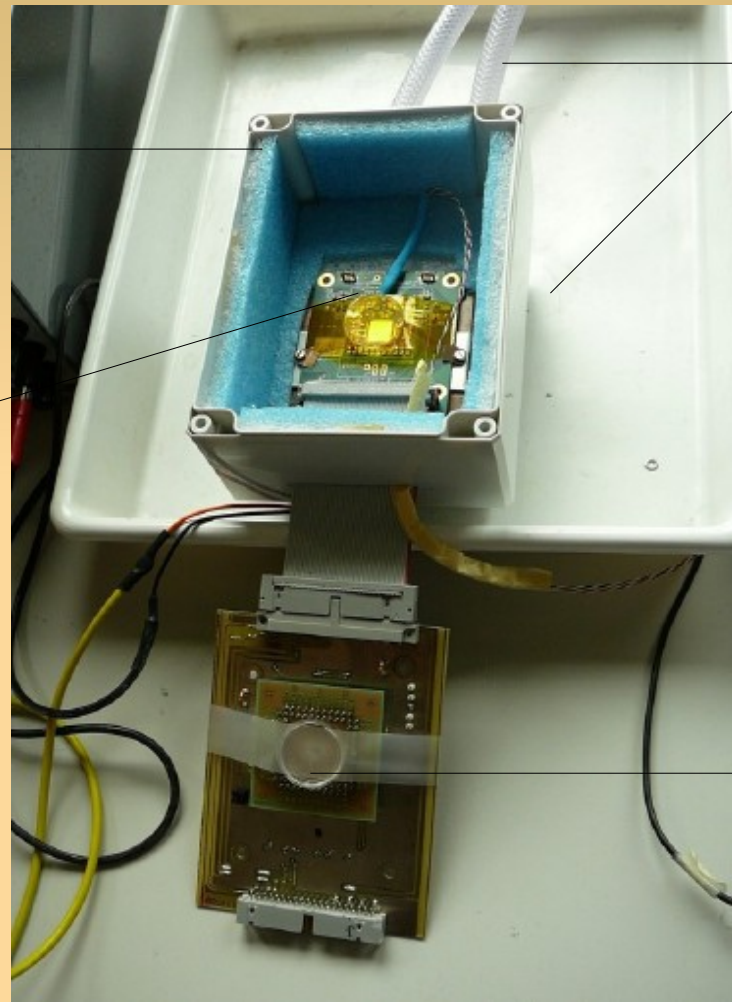
- Pions (300 MeV, PSI, Aug 2007)
  - 14 samples up to  $6.2 \times 10^{14}$  Neq/cm<sup>2</sup>
  - Irradiation was not smooth, lost several days of good beam
  - Thanks
    - Maurice Glaser (CERN)
    - Mark Gerling and Christopher Betancourt (UCSC)
    - Financial support from RD50
- Protons (26 GeV, CERNPS, July 2007)
  - 32 samples up to  $5.1 \times 10^{15}$  Neq/cm<sup>2</sup>
  - Went smoothly
    - thanks to Maurice Glaser and the CERN team
  - Transport of samples out of CERN difficult

# Setup Description

The Cooling box was Flushed with dry N<sub>2</sub>.

Humidity and temperature sensors  
-H<5%

Sr90 source (~2 MBq)



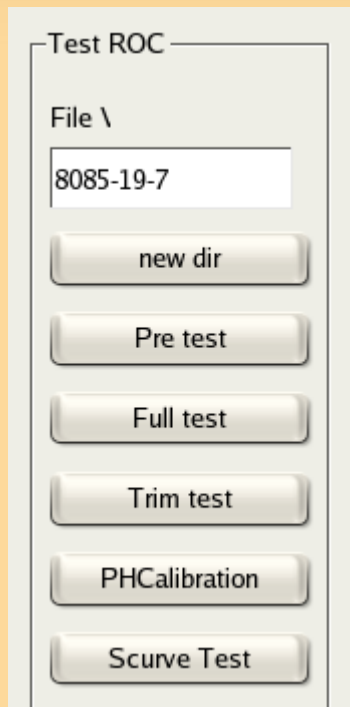
Colling with Peltier system  
-T~-10° C

Random triggers

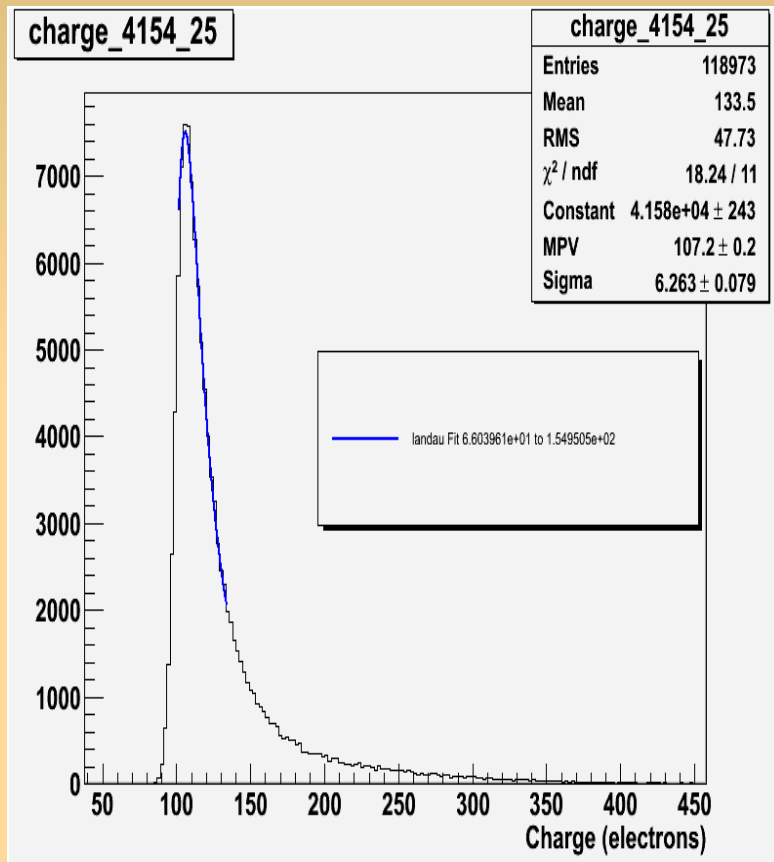
- Sensitive clock cycle
- stretched by a large factor
- **Efficiency ~80%**

# Calibration procedure

- For each sensor we reduced the temperature
  - Temperature during the test  $\sim -10^{\circ}$  C
- Dry with  $N_2$ 
  - Humidity during the test  $< 5\%$ 
    - Calibrate the sensor at  $B_{bias} = -150V$ 
      - Pretest (find the correct Dac Parameters).
      - Fulltest (Test address decoding pixel by pixel ).
      - Trim Test (small pixel by pixel threshold corrections)
      - Pulse Height Calibration (Calibration between signal in (Vcal) and signal out “Pulse Height” per pixel).
      - S-Curve Test (to scan noise pixel by pixel).

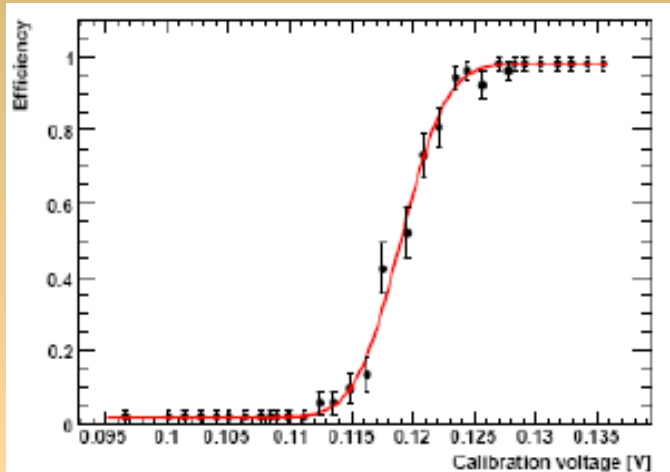


# Test Procedure



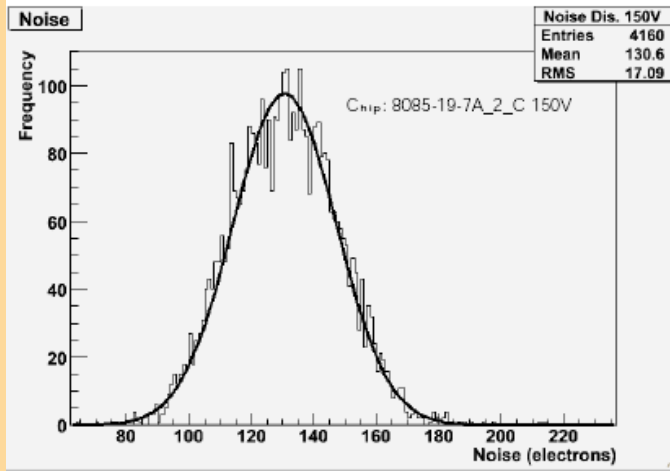
- For each sensor we varied the Vbias from -25V to -600V
- For each Vbias Value:
  - “S-curve test” to calculate noise variations.
  - Take data with Sr-90 source

# Noise measurement (“S-curve Test”)



Typical S-curve From: S. Dambach, C. Egge, P. Trub.  
DAC Optimization of the Pixel Detector Readout Chip.  
CMS Note 2005/000, 2008.

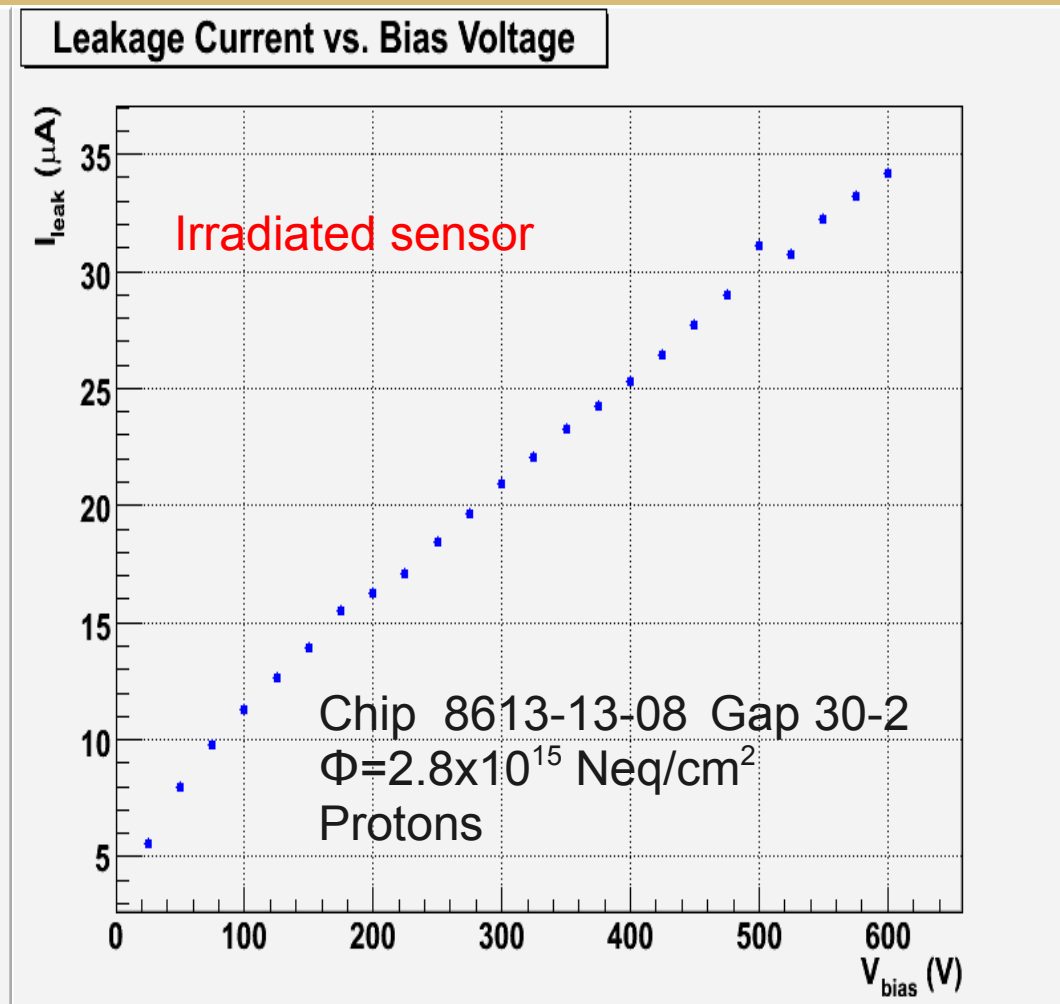
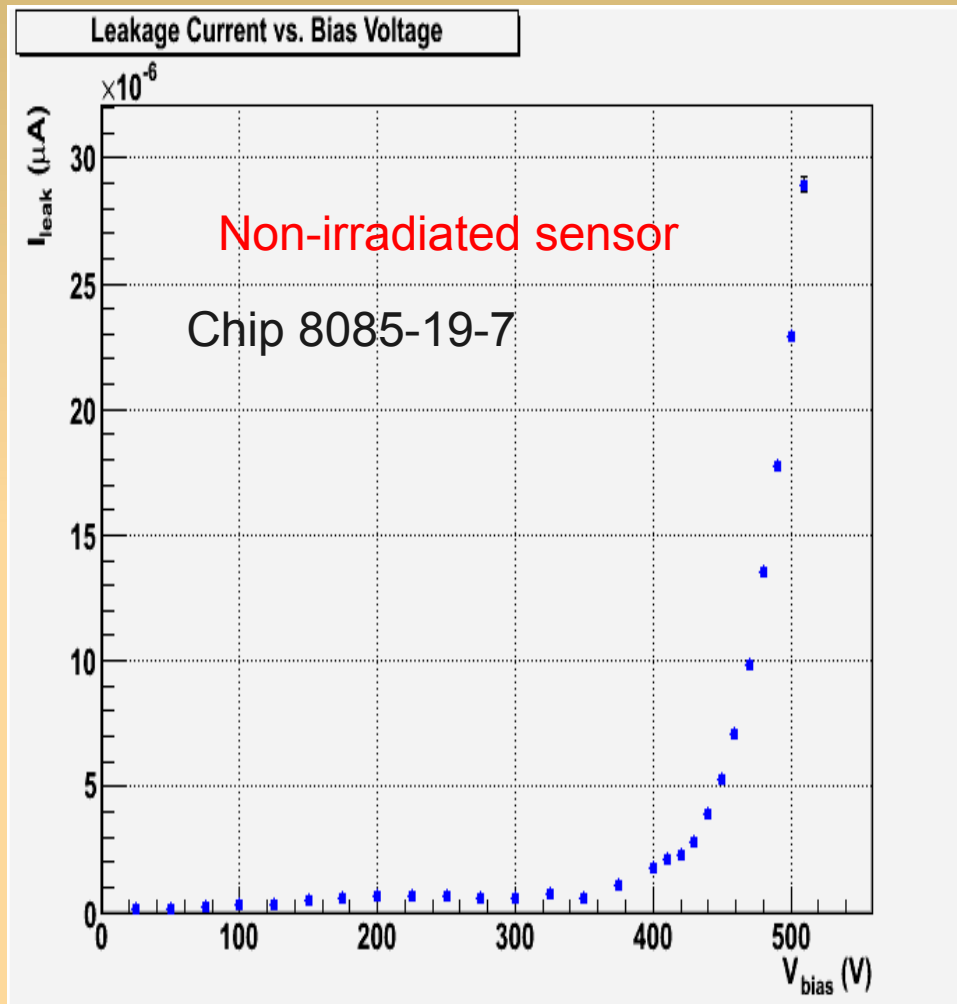
$$\text{Fit}(x) = P_0 \cdot \text{Erf}(P_2(x - P_1)) + P_3 \quad \text{Erf}(y) = \frac{2}{\sqrt{\pi}} \int_0^y e^{-t^2} dt$$



- For each pixel fix the threshold Voltage, and send n signals with different amplitude.
  - Increase the value of the amplitude of signal (calibration voltage).
  - Measure the efficiency (top graph)
  - Fit with error function to determine sigma.
- $$\sigma = \frac{1}{P_2 \cdot \sqrt{2}}$$
- Build the distribution for each sensor and calculate the mean.

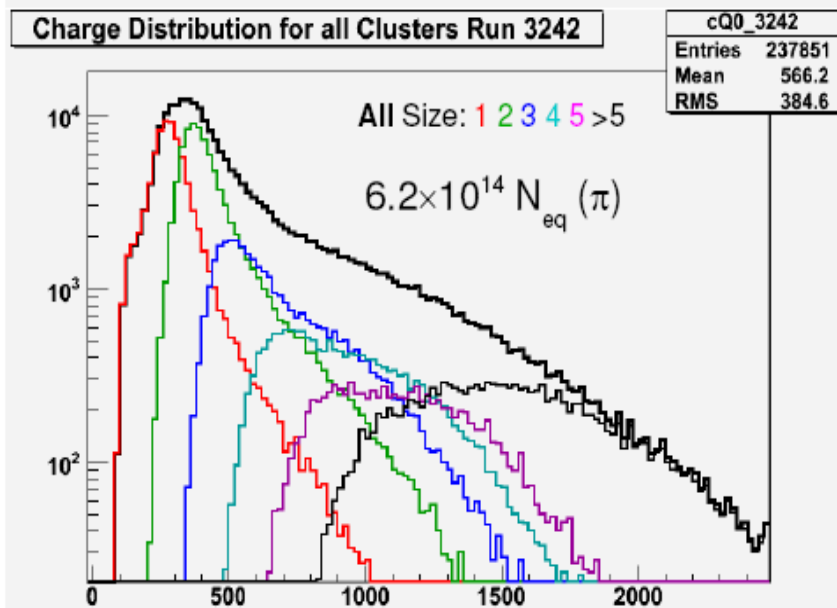
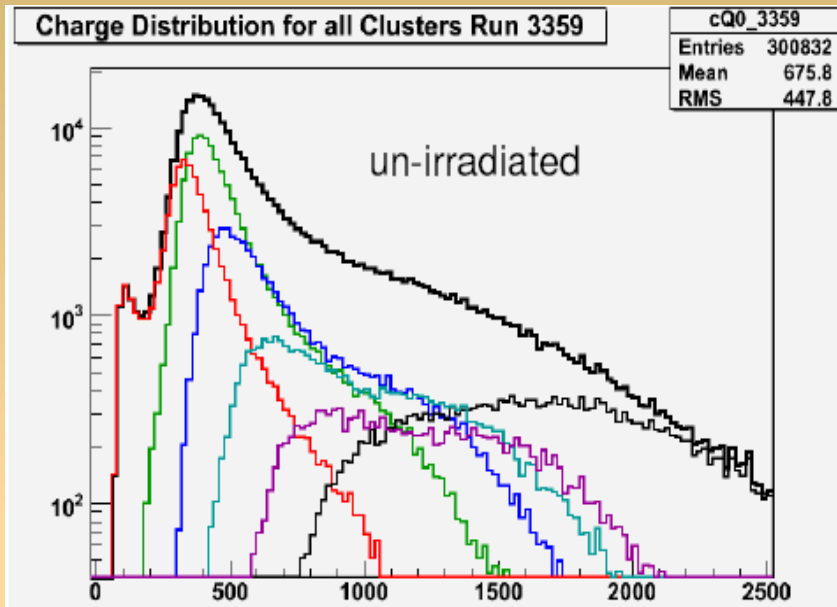


# Leakage Current



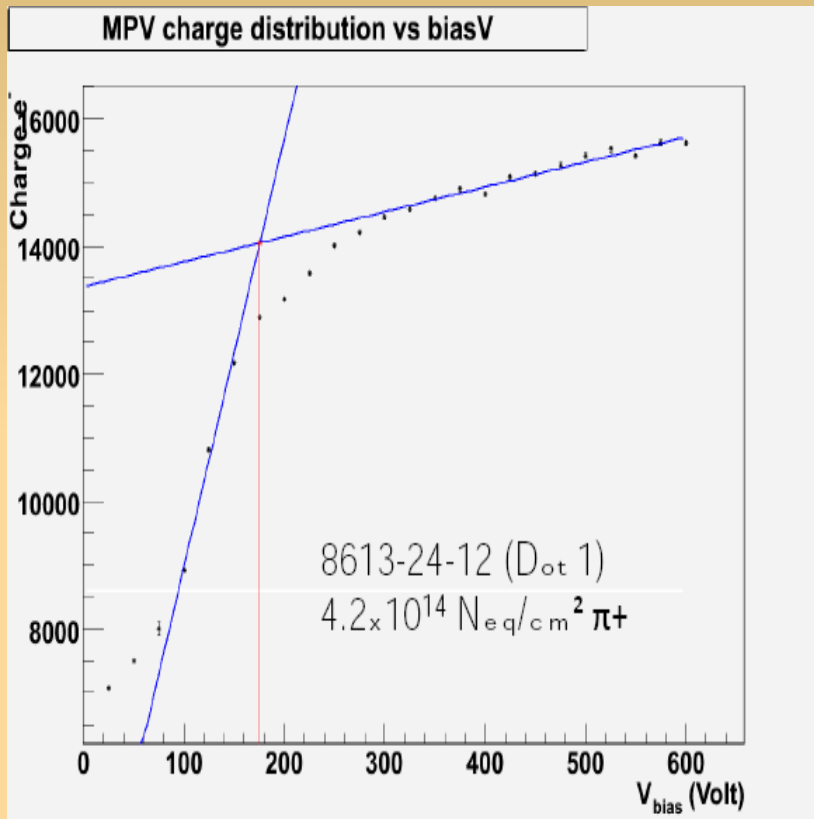
- Simply measure the current for each  $V_{\text{bias}}$  across the sensor

# Pulse Height Spectra



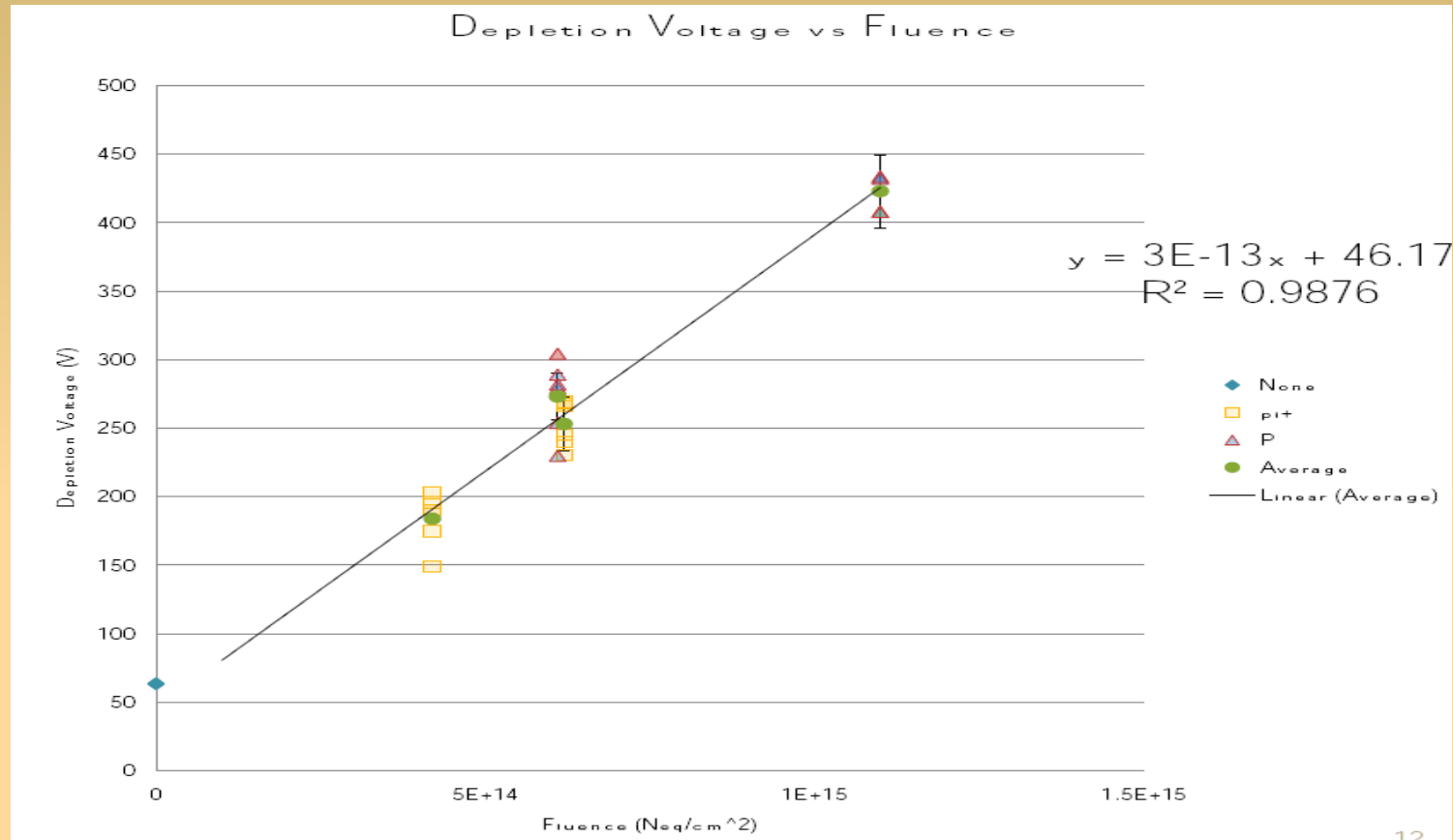
- Landau-like shape only for clusters < 3 pixels
  - Large cluster come from:
    - low energetic electrons
    - deltas
- Pulse height depends on cluster size
  - Restrict to 1(+2) hit clusters
  - Fit Landau convoluted with a Gaussian.
  - Peak of low signals in 1-hit clusters

# Depletion Voltage estimation



- For each  $V_{bias}$  we Fit charge distribution from Sr-90 source using Landau convoluted function, and take the MPV (most probable value).
- Build the graph MPV vs  $V_{bias}$ 
  - Extrapolate a line from points where sensor is Depleted
  - Another from the points where the Charge Collection is increasing
  - Intersection is what we call the Depletion Voltage

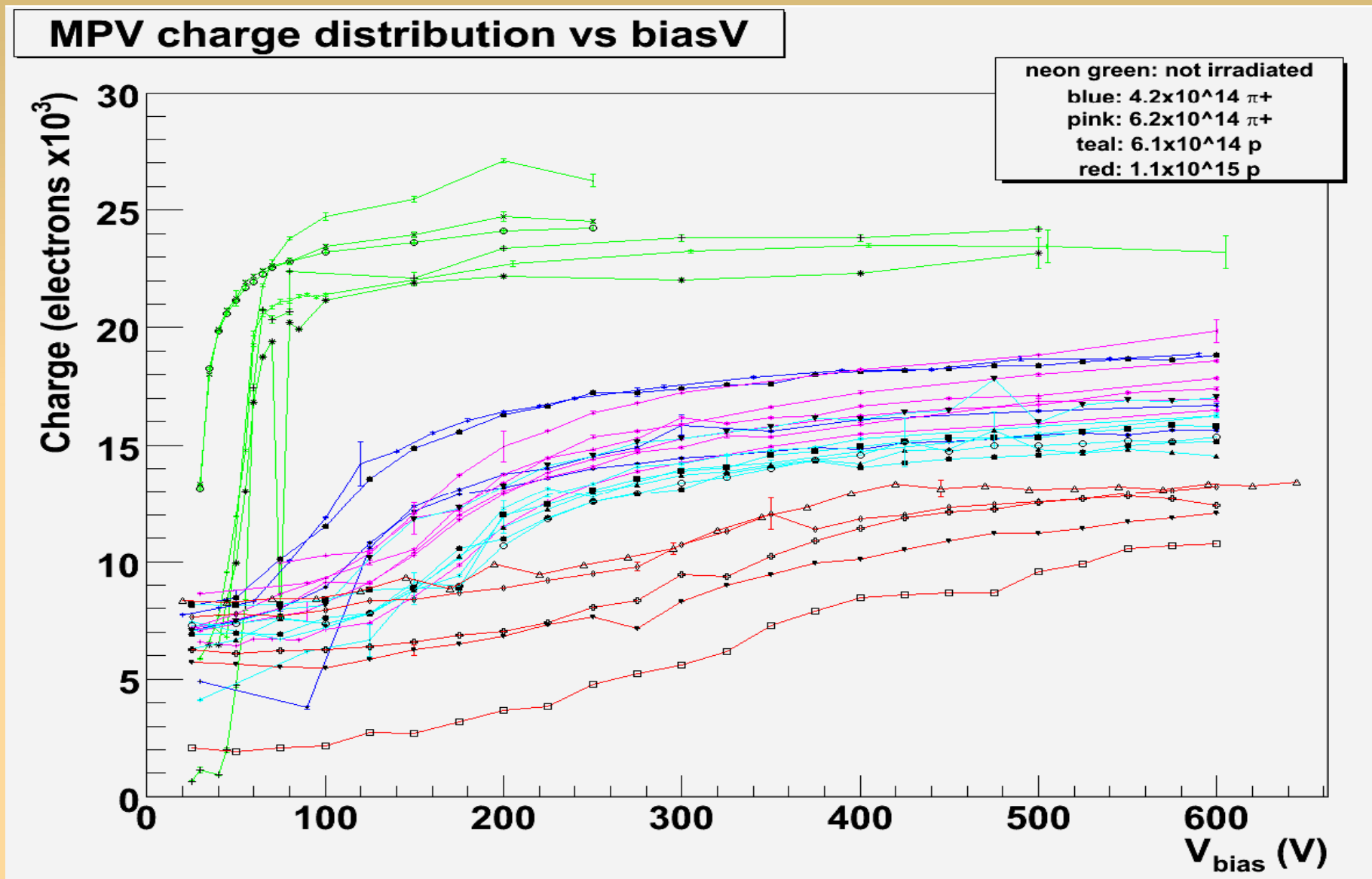
# Depletion voltage



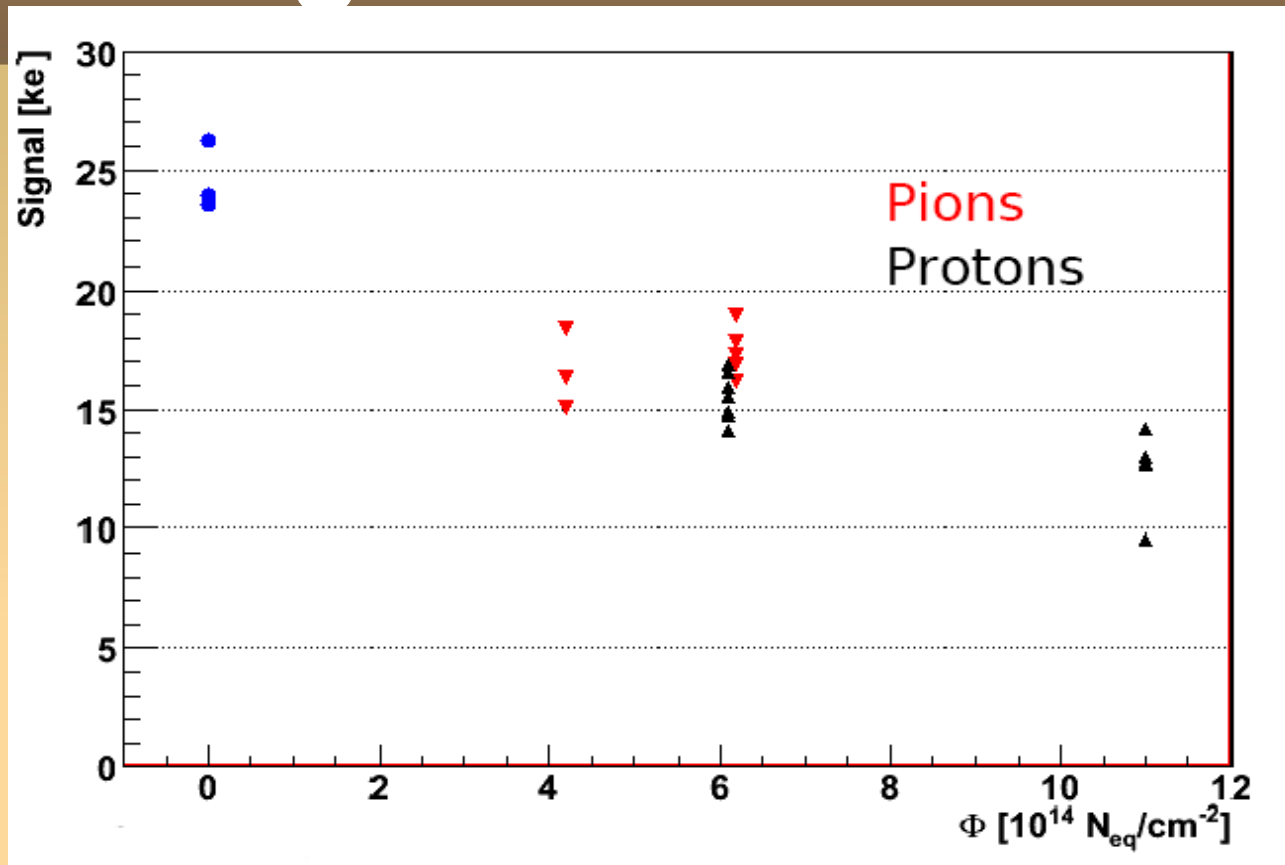
$$V_{depletion} = 3 \cdot 10^{-13} \left[ \frac{\text{Volt cm}^2}{\text{Neq}} \right] \left( \text{Fluence} \left[ \frac{\text{Neq}}{\text{cm}^2} \right] \right) + 46.17 [\text{Volt}]$$

The Values are spread in irradiated sensors and there are large uncertainties in the method

# Charge collection vs Vbias



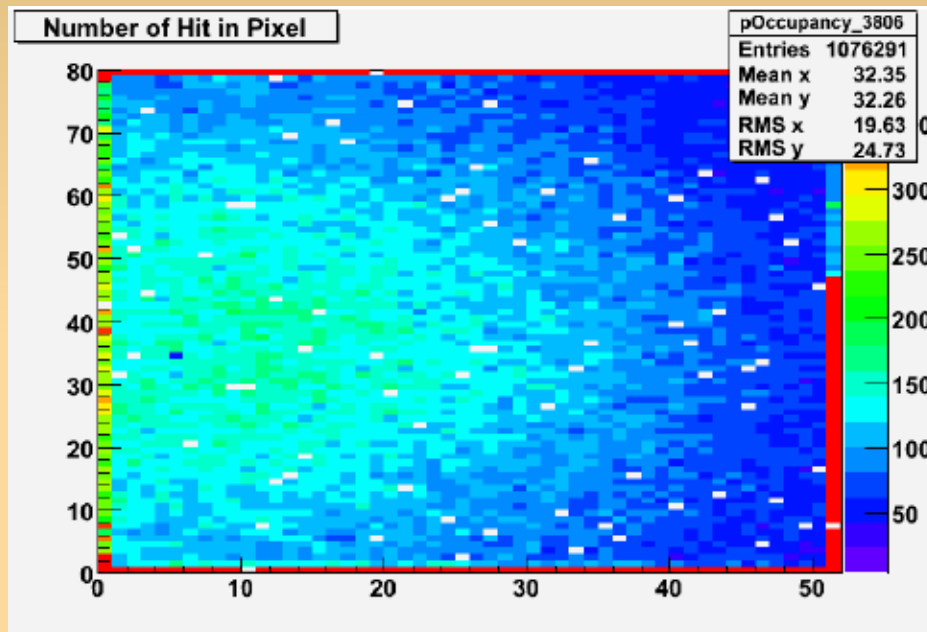
# Signal vs Fluence



- Large spread between samples
  - Problems with calibration?
  - Excluded
    - Wafer thickness variations
    - Small temperature variations

# What is above $10^{15}$ ?

- For samples with  $\Phi \gg 10^{15}$ 
  - ROC operation becomes difficult
  - Dacs have to be adjusted which are not part of the standard calibration procedure
  - Has to be done manually by expert (not me)
- (Not yet succeeded)
  - For a sample with  $2.8 \times 10^{15}$  Neq/cm<sup>2</sup> particles are clearly



seen, but no quantitative measurements yet.

# Conclusions

- Charge Collection studies could reproduce the values from previous measurements.
- • Measurements for fluences  $> 10^{15}$  Neq/cm<sup>2</sup>
- See particles
  - No quantitative measurement yet
- Short term
  - Understand the operation of highly irradiated ROCs
  - Understand the reason for the wide spread
  - Analysis of 2hit clusters
- Longer term
  - Scintillator trigger
  - Efficiency measurement
  - Cut of low energetic electrons
  - Better cooling